

P-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | | |
|---------------------|--------------------------------------|---------------------------------|-----------------------|--|--|--|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) ^a | Q _g (Typ.) | | | | |
| - 30 | 0.049 at V _{GS} = - 10 V | - 4.8 5.1 nC | | | | | |
| | 0.054 at $V_{GS} = -4.5 \text{ V}$ | - 4.1 | 5.1110 | | | | |

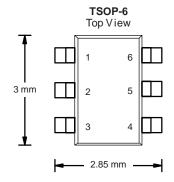
FEATURES

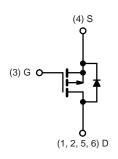
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET



APPLICATIONS

· Load Switch





P-Channel MOSFET

| Parameter | | Symbol | Limit | Unit | |
|---|------------------------|-----------------------------------|------------------------|------|--|
| Drain-Source Voltage | | V _{DS} | - 30 | V | |
| Gate-Source Voltage | | V_{GS} | ± 20 | 7 v | |
| | T _C = 25 °C | | - 4.8 | | |
| Continuous Drain Current (T _{.1} = 150 °C) | T _C = 70 °C | | - 4.1 | | |
| Continuous Drain Current (1) = 130 °C) | T _A = 25 °C | - I _D | - 4.0 ^{b, c} | А | |
| | T _A = 70 °C | 1 | - 3.5 ^{b, c} | | |
| Pulsed Drain Current | • | I _{DM} | - 20 | | |
| | T _C = 25 °C | | - 2.5 | | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | l _S | - 1.67 ^{b, c} | | |
| | T _C = 25 °C | | 3.0 | W | |
| Maximum Pawar Dissipation | T _C = 70 °C | D_ | 2.0 | | |
| Maximum Power Dissipation | T _A = 25 °C | P_{D} | 2.0 ^{b, c} | | |
| | T _A = 70 °C | 1 1 | 1.3 ^{b, c} | | |
| Operating Junction and Storage Temperature | e Range | T _J , T _{stg} | - 55 to 150 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | | | |
|---|--------------|------------|---------|------|-------|--|--|
| Parameter | Symbol | Typical | Maximum | Unit | | | |
| Maximum Junction-to-Ambient ^{b, d} | t ≤ 5 s | R_{thJA} | 55 | 62.5 | °C/W | | |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 34 | 41 | 5/ ۷۷ | | |

Notes:

- a. Based on T_C = 25 °C.
 b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 110 °C/W.

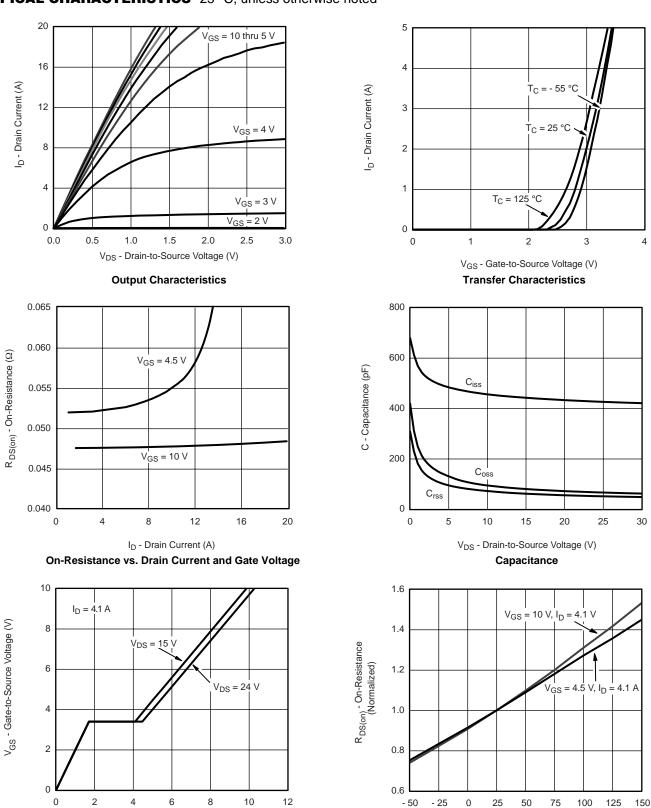


| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit |
|---|-------------------------|--|-------|----------|-------|-------|
| Static | | | | | l | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$ | - 30 | | | V |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | J 250 A | | - 31 | | mV/°C |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = - 250 μA | | 4.5 | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | - 0.5 | | - 2.0 | V |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA |
| Zana Oata Vallana Brain Oamant | , | $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ | | | - 1 | μΑ |
| Zero Gate Voltage Drain Current | IDSS | $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$ | | | - 10 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$ | - 20 | | | Α |
| | | V _{GS} = - 10 V, I _D = - 4.1 A | | 0.049 | | Ω |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 4.5 V, I _D = - 1.0 A | | 0.054 | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 15 V, I _D = - 4.1 A | | 8 | | S |
| Dynamic ^b | | | | <u> </u> | | |
| Input Capacitance | C _{iss} | | | 450 | | pF |
| Output Capacitance | C _{oss} | $V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 80 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 63 | | |
| Total Gate Charge | Qg | V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 4.1 A | | 10 | 15 | nC |
| | | | | 5.1 | 8 | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -4.1 \text{ A}$ | | 1.8 | | |
| Gate-Drain Charge | Q_{gd} | | | 2.5 | | |
| Gate Resistance | R_{g} | f = 1 MHz | | 7 | | Ω |
| Turn-On Delay Time | t _{d(on)} | | | 40 | 60 | |
| Rise Time | t _r | $V_{DD} = -15 \text{ V}, R_{L} = 4.6 \Omega$ | | 80 | 120 | 1 |
| Turn-Off Delay Time | t _{d(off)} | $I_D\cong$ - 3.3 A, V_{GEN} = - 4.5 V, R_g = 1 Ω | | 20 | 30 | ns |
| Fall Time | t _f | | | 12 | 20 | |
| Turn-On Delay Time | t _{d(on)} | | | 5 | 10 | |
| Rise Time | t _r | V_{DD} = - 15 V, R_L = 4.6 Ω | | 13 | 20 | |
| Turn-Off Delay Time | t _{d(off)} | $I_D\cong$ - 3.3 A, V_{GEN} = - 10 V, R_g = 1 Ω | | 20 | 30 | |
| Fall Time | t _f | | | 10 | 15 | |
| Drain-Source Body Diode Characteristi | cs | | | | | |
| Continuous Source-Drain Diode Current | Is | T _C = 25 °C | | | - 2.5 | ^ |
| Pulse Diode Forward Current ^a | I _{SM} | | | | - 20 |] A |
| Body Diode Voltage | V _{SD} | I _S = - 3.3 A | | - 0.8 | - 1.2 | V |
| Body Diode Reverse Recovery Time | t _{rr} | | | 20 | 30 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | 1 22 A di/d+ 400 A/ T 05 00 | | 20 | 30 | nC |
| Reverse Recovery Fall Time | t _a | $I_F = -3.3 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$ | | 14 | | 1 |
| Reverse Recovery Rise Time | | t _b | | 6 | | ns |

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





服务热线:400-655-8788

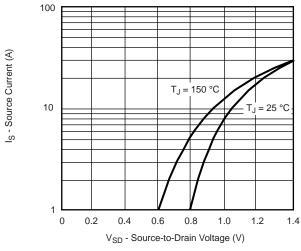
Q_q - Total Gate Charge (nC)

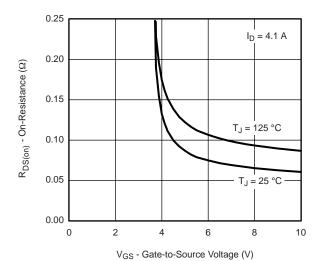
Gate Charge

T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

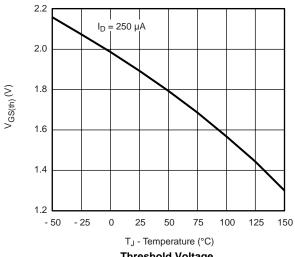


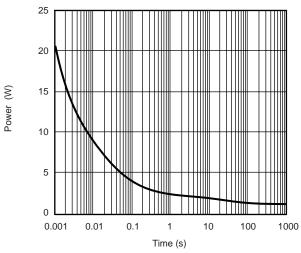




Source-Drain Diode Forward Voltage

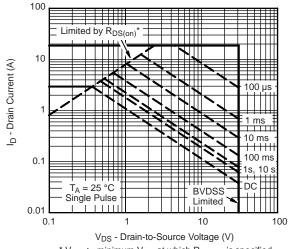






Threshold Voltage

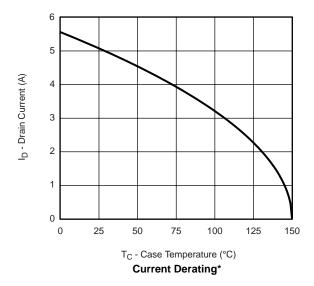
Single Pulse Power

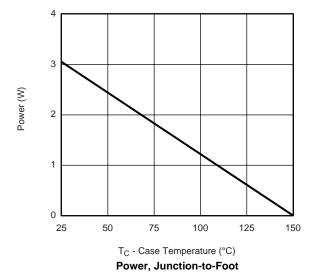


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

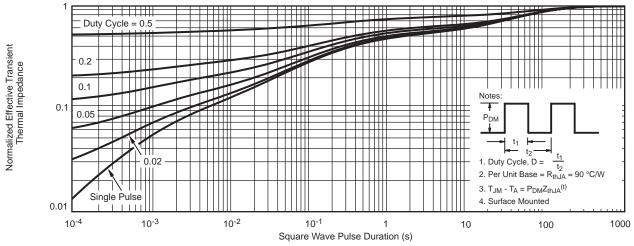




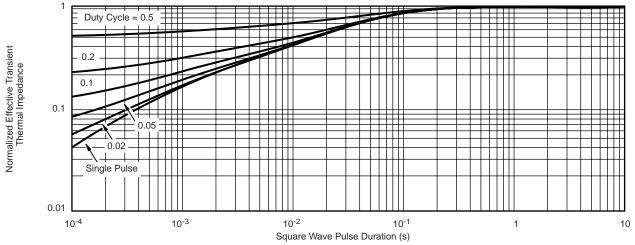


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

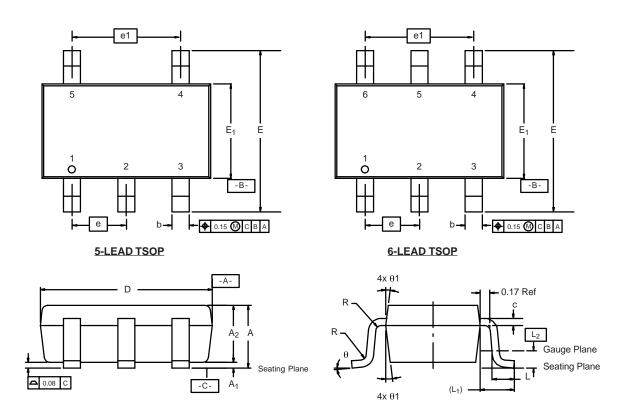


Normalized Thermal Transient Impedance, Junction-to-Foot



TSOP: 5/6-LEAD

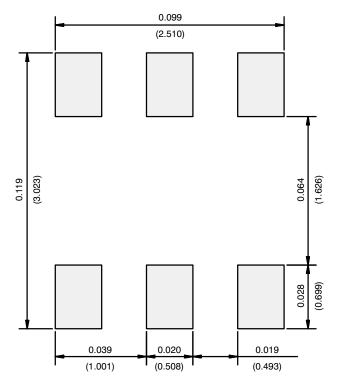
JEDEC Part Number: MO-193C



| | MILLIMETERS | | | INCHES | | | |
|---|-------------|------|------|------------|-------|-------|--|
| Dim | Min | Nom | Max | Min | Nom | Max | |
| Α | 0.91 | - | 1.10 | 0.036 | - | 0.043 | |
| A ₁ | 0.01 | - | 0.10 | 0.0004 | - | 0.004 | |
| A ₂ | 0.90 | - | 1.00 | 0.035 | 0.038 | 0.039 | |
| b | 0.30 | 0.32 | 0.45 | 0.012 | 0.013 | 0.018 | |
| С | 0.10 | 0.15 | 0.20 | 0.004 | 0.006 | 0.008 | |
| D | 2.95 | 3.05 | 3.10 | 0.116 | 0.120 | 0.122 | |
| Е | 2.70 | 2.85 | 2.98 | 0.106 | 0.112 | 0.117 | |
| E ₁ | 1.55 | 1.65 | 1.70 | 0.061 | 0.065 | 0.067 | |
| е | 0.95 BSC | | | 0.0374 BSC | | | |
| e ₁ | 1.80 | 1.90 | 2.00 | 0.071 | 0.075 | 0.079 | |
| L | 0.32 | - | 0.50 | 0.012 | - | 0.020 | |
| L ₁ | 0.60 Ref | | | 0.024 Ref | | | |
| L ₂ | 0.25 BSC | | | 0.010 BSC | | | |
| R | 0.10 | - | - | 0.004 | - | - | |
| θ | 0° | 4° | 8° | 0° | 4° | 8° | |
| θ_1 | 7° Nom | | | 7° Nom | | | |
| ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540 | | | | | | | |



RECOMMENDED MINIMUM PADS FOR TSOP-6



Recommended Minimum Pads Dimensions in Inches/(mm)



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